


Features

- Surface Mounting Design 7.8×5.0×6.0mm
- High Current Handling Capability 5,000A @ 8/20 μs
- Low Capacitance and Insertion Loss
- Quick Response and Long Service Life
- Moisture sensitivity level: Level 1

Application Information

- DC30V Power

Agency Approvals

Icon	Description
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free

Electrical Parameter

DC Breakdown Voltage ¹⁾²⁾	100V/s	245-455	V
Impulse Spark-over Voltage	At 1kV/μs	for 99 % of measured values	≤ 850
	At 1kV/μs	Typical values of distribution	≤ 700
Impulse Discharge Current ³⁾	8/20μs, ±5T	5,000	A
Arc Voltage	At 1A	>33	V
Insulation Resistance	DC=100V	≥1	GΩ
Capacitance at 1MHz	VDC=0.5V	≤1.5	pF
Weight		~1.1	g
Operating And Storage Temperature		-40-90	°C
Marking		D35R	

1) At delivery AQL 0.65 level II GB/T 2828.1-2003

2) In ionized mode

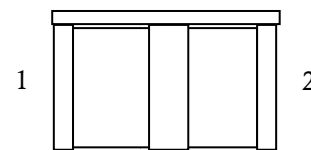
3) Terms and waveforms in accordance with ITU-T Rec. K. 12; IEC 61643-21

Exterior

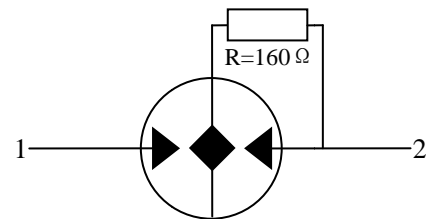


SMD

Package (Top View)



Schematic Symbol



Part Numbering System

B3D xxx M - R
(1) (2) (3) (4)

(1) Bencent 3-Electrode SMD Gas Discharge Tube
7.8×5.0×6.0mm

(2) DC Breakdown Voltage, e.g., 350=350V

(3) Surge Rating @8/20 μs, M=5,000A

(4) Resistance Triggering

Product Characteristics

Lead Material	Copper
Body Material	Ceramics
Terminal Finish	100% Matte-Tin Plated

Environmental Reliability Characteristics

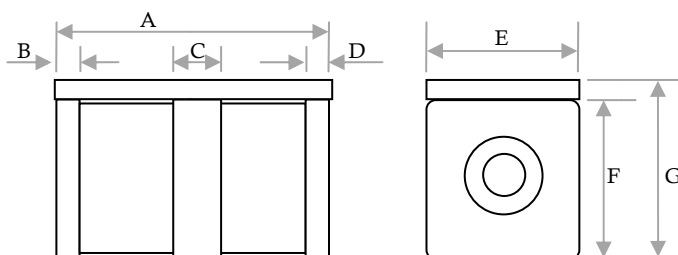
Testing items	Technical standards
High Temperature Storage Test	Temperature: 90°C Time:2H
Low Temperature Storage Test	Temperature: -40°C Time:2H
Vibration	Frequency: 10-500Hz Amplitude: 0.15mm Time: 45min
Resistance of soldering heat	Temperature: 260±5°C Time of dip soldering: 10s, 1time

Note: Up-screen program can be specified by customer's request via contacting Bencent service

Solderability Test

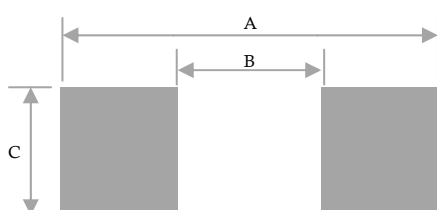
Solderability	Solder Pot Temperature:	245°C ± 5°C
	Solder Dwell Time:	4-6 secs.

Product Dimensions



REF	mm	inch
A	7.8±0.3	0.307±0.012
B	0.5±0.2	0.020±0.008
C	1.6±0.2	0.063±0.008
D	0.5±0.2	0.020±0.008
E	5.0±0.2	0.197±0.008
F	5.0±0.2	0.197±0.008
G	6.0±0.3	0.236±0.012

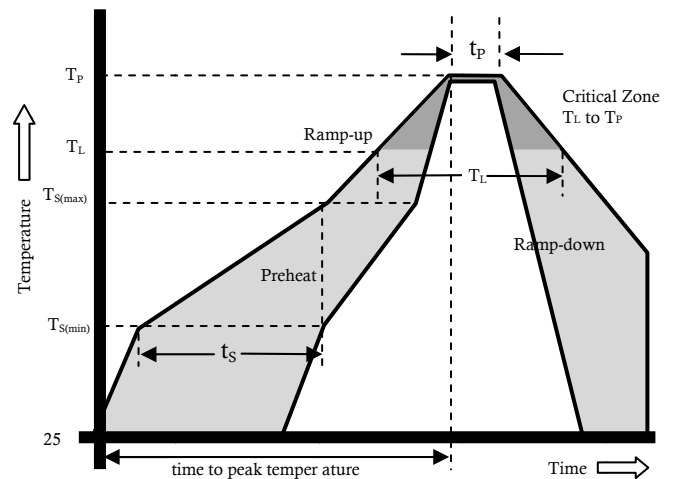
Recommended Soldering Pad



REF	mm	inch
A	9.6	0.378
B	6.6	0.260
C	5.0	0.197

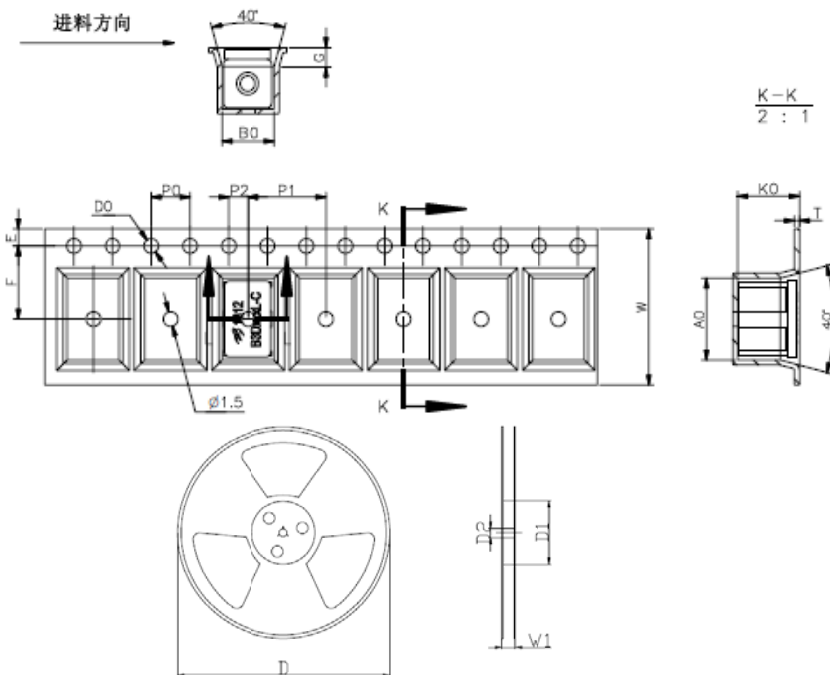
Reflow Profile

Reflow Condition		Pb-Free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (min to max)	60 – 180 secs.
Average ramp up rate (Liquids) T _{amp} (T _L) to peak		3°C/second max
T _S (max) to T _L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T _L) (Liquids)	217°C
	- Temperature (T _L)	60 – 150 secs.
Peak Temperature (T _P)		260+0/-5 °C
Time within 5°C of actual peak Temperature (t _p)		~10 secs
Ramp-down Rate		6°C/secs. max
Time 25°C to peak Temperature (T _P)		8 minutes Max.
Do not exceed		260°C



Remarking: it's only suitable for SMT manufacture, not for manual welding.

Package Reel Information



REF	mm	inch
A0	8.4±0.2	0.331±0.008
B0	5.4±0.2	0.216±0.008
P0	4.0±0.2	0.157±0.008
P1	8.0±0.2	0.315±0.008
P2	2.0±0.2	0.079±0.008
E	1.75±0.2	0.069±0.008
F	7.5±0.2	0.295±0.008
K0	6.3±0.2	0.248±0.008
T	0.5±0.2	0.020±0.008
G	2	0.079
D0	Φ 1.5±0.2	Φ 0.059±0.008
W	16.0±0.3	0.630± 0.012
D	Φ 330.0	Φ 13.0
D1	Φ 50Min	Φ 1.97Min
D2	Φ 13±0.5	Φ 0.512±0.020
W1	16.8±0.5	0.661±0.020

Outline	Reel (PCS)	Per Carton (PCS)	Reel Diameter (mm)	Carton Size(mm)		
				L	W	H
TAPING	1,000	16,000	330	360	360	385